

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC025N03LS G	**Issued**	04. April 2021
MA#	MA001620428		
Package	PG-TDSON-8-39	**Weight***	112.92 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	2.12	2.12	21176	21176
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		431	
	non noble metal	copper	7440-50-8	48.649	43.09	43.14	430832	431392
wire	non noble metal	copper	7440-50-8	0.042	0.04	0.04	368	368
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		722	
	plastics	epoxy resin	-	6.437	5.70		57002	
	inorganic material	silicondioxide	60676-86-0	34.220	30.30	36.07	303049	360773
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13461	13461
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1403	1403
solder	non noble metal	tin	7440-31-5	0.046	0.04		403	
	noble metal	silver	7440-22-4	0.057	0.05		504	
	non noble metal	lead	7439-92-1	2.173	1.92	2.01	19243	20150
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1329	
	non noble metal	copper	7440-50-8	16.910	14.98	15.13	149753	151277
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com